

Material Composition Specification

SOT-363 Case



Device average mass **5.9 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	3.38%	0.2	Si	7440-21-3	3.38%	0.2	33,841
bond wire	gold	0.68%	0.04	Au	7440-57-5	0.68%	0.04	6,768
leadframe	alloy 42 w/ silver plating	33%	1.95	Fe	7439-89-6	19.12%	1.13	191,201
				Ni	7440-02-0	13.2%	0.78	131,980
				Ag	7440-22-4	0.68%	0.04	6,768
encapsulation*	EMC	58.21%	3.44	silica	7631-86-9	41.96%	2.48	419,628
				epoxy resin	Proprietary	14.55%	0.86	145,516
				Sb ₂ O ₃	1309-64-4	1.18%	0.07	11,844
				TBBA	79-94-7	0.34%	0.02	3,384
				carbon	1333-86-4	0.17%	0.01	1,692
	EMC GREEN	58.21%	3.44	silica	60676-86-0	38.9%	2.299	389,048
				epoxy resin	29690-82-2	8.84%	0.522	88,365
				phenol resin	9003-35-4	4.43%	0.262	44,333
				carbon black	1333-86-4	0.3%	0.018	3,016
				metal hydroxide	1309-42-8	5.73%	0.339	57,302
plating**	tin/lead process	4.74%	0.28	Sn	7440-31-5	3.98%	0.23	39,763
				Pb	7439-92-1	0.76%	0.04	7,614
	matte tin	4.74 %	0.28	Sn	7440-31-5	4.74%	0.28	47,377

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R6 (3-June 2011)